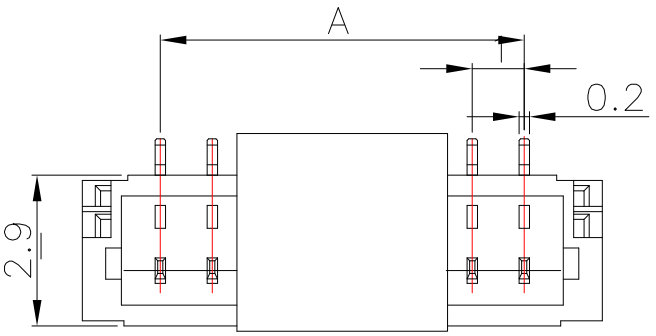
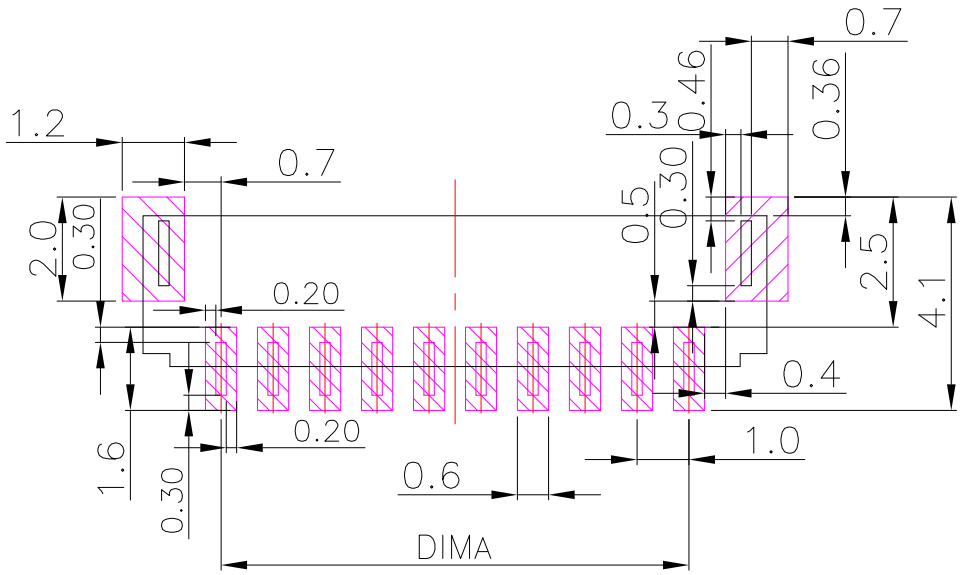
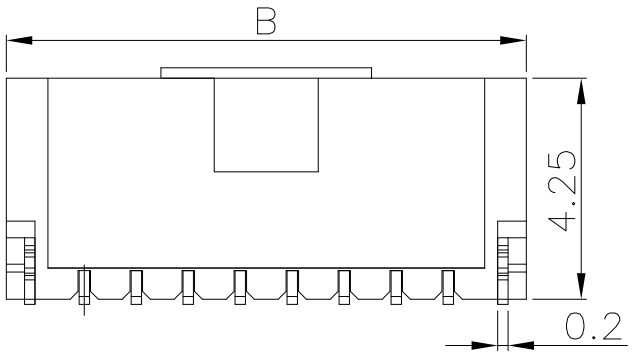
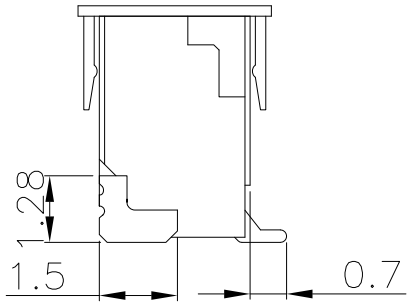




P.C.B LAYOUT MOUNTING PATTERN





PIN NO.	DIMENSION	
	A	B
02	1.00	4.00
03	2.00	5.00
04	3.00	6.00
05	4.00	7.00
06	5.00	8.00
07	6.00	9.00
08	7.00	10.00
09	8.00	11.00
10	9.00	12.00
11	10.00	13.00
12	11.00	14.00
13	12.00	15.00
14	13.00	16.00
15	14.00	17.00
16	15.00	18.00
17	16.00	19.00
18	17.00	20.00
19	18.00	21.00
20	19.00	22.00

1.MATERIAL
HOUSING:HTN
CONTACT:PHOSPHOR BRONZE
SOLDER PAD:BRASS
2.PLATING: TIN OVER NICKEL
3.SPECIFICATION
CURRENT RATING:1A AC,DC
VOLTAGE RATING:250V AC,DC
TEMPERATURE RANGE:-25C~+85C
CONTACT RESISTANCE:20M MAX.
INSULATION RESISTANCE:1000M MIN.
WITHSTANDING VOLTAGE:500V AC/MINUTE

ITEM NO.	DESCRIPTION	DRAWN	DATE
4	更新材質	Jack	121422
3	更新PCB LAYOUT	Jack	091420
2	更新PCB LAYOUT	Jack	032118
1	更新B尺寸標示位置	Jack	101515

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2; Above 5 ~ 15 ±0.3; Above 15 ~ 30 ±0.4; Above 30 ~ 50 ±0.5; Angle ±0.3°

3RD. ANGEL'S | UNITS MM

		DATE
DRAWN BY:	Jack Lu	12/14/22
CHECKED BY:	Jacky Chen	12/14/22
APPROVED BY:	Tony Kao	12/14/22

MAT'L		TITLE	CONNECTOR
FINISH		MODLE	WAFER 1.0 SMT 180度(JST)
SCALE	1 : 1	DWG NO.	WF-1000VSxx-S304
SHEET NO.	1 of 1	PART NO.	WF-1000VSxx-S304

SIZE A4 | VER R4